



SOLDER PASTE Water soluble « CASCADE™ 1 »



Creation date : 20/05/2009 Update : 01/02/2016 Index : 04



DESCRIPTION

CASCADE™ 1 water-soluble solder paste has been developed in MBO laboratories and is carefully formulated to confer high activity soldering. Its residues can be easily removed with deionised water. This product, suitable for printing applications meets the international requirements of the electronics industry.

- **ORL0 classification (J-STD-004)**
- Halide free
- Good activity.
- Water soluble low residues.
- Very good tack-life = 16 hours
- Good slump resistance
- Available in type 3, 4 and 5. Other : consult us.

CASCADE™ 1 water soluble solder paste is manufactured in compliance with the international standards.

AVAILABLE ALLOYS

Alloy	Alloy number ISO 9453 (2014)	Melting Point (°C)	Metal content (%)	Viscosity (Pas) J-STD 005
Sn62Pb36Ag2	171	179	90	180 - 220
Sn63Pb37	101	183	90	180 - 220
Other : consult us				



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TECHNICAL DATA

Category	Standard	Results
Activity Level (classification)	IPC J-STD-004	ORL0
Halide Content	IPC J-STD-004	Halide free (by titration)
Silver Chromate	IPC-TM-650 (2.3.33)	Pass
Visual aspect of residues	IPC-HDBK-005	Brown Clear
Viscosity	Malcom spiral viscometer (J-STD-005)	200 Pa.s
Solder ball test	IPC J-STD-005	Acceptable

PRINTING

Stencil

Stainless steel, brass or nickel. Chemical cut, laser cut or electroformed.

Squeegee

Stainless steel (recommended) or 80-100 durometer polyurethane.

Print speed

20-80 mm/s. Generally slower for fine pitch.

Squeegee pressure

0.15-0.3 Kg/cm of squeegee length

Snap-off

0 to 0.25mm. On contact printing is preferred.

Ambient conditions

21-26°C and 35% to 60% RH. Minimize exposure of paste direct to air flow.

Cleanup-Stencils and Tools

Water, water based cleaners.



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REFLOW

Heating Methods

Convection, infrared, vapour phase, hot plate, hot bar, laser and others. Aerobic or inerted.

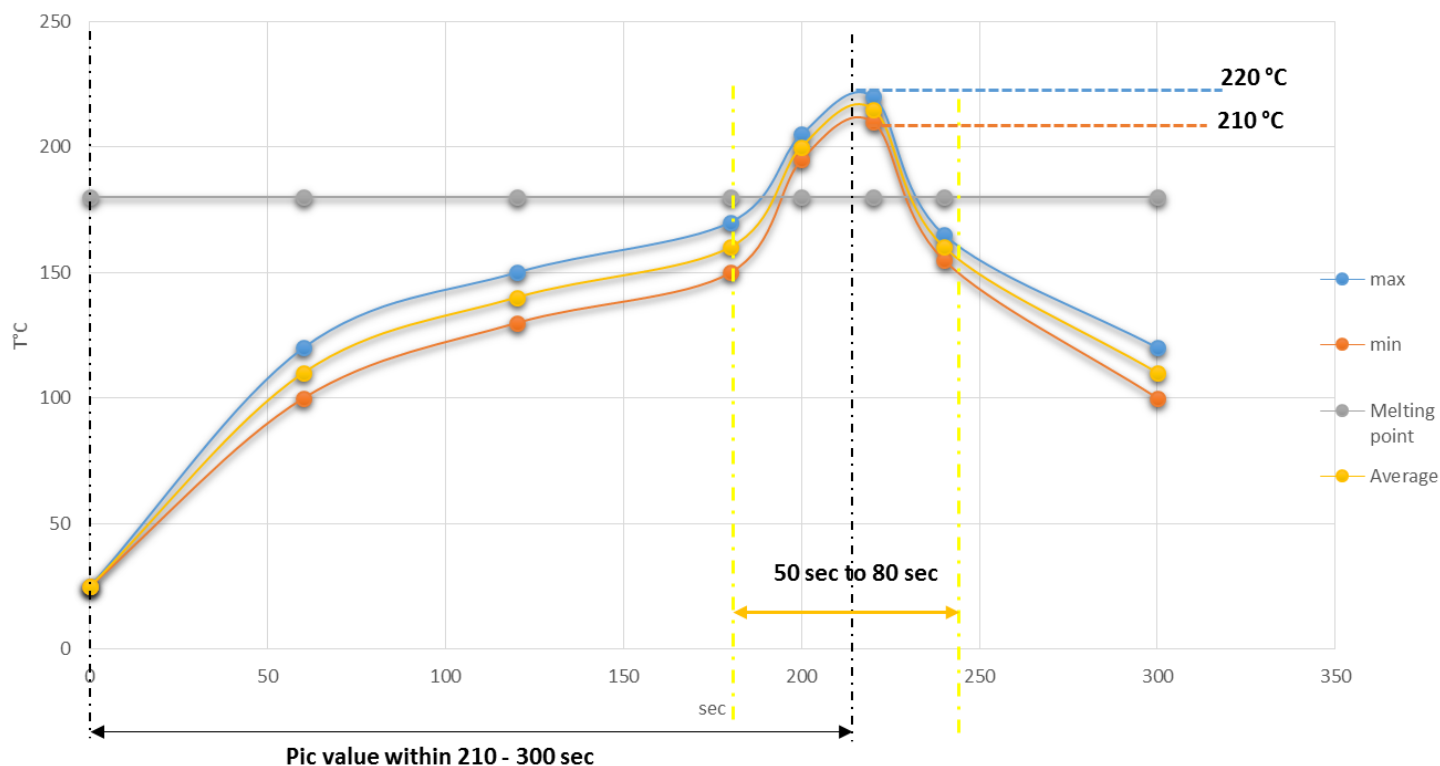
Heating Profile

See suggested reflow profile for specific alloy.

Cleaning

The post-soldered residue of CASCADE 1 is not particularly corrosive but is hygroscopic. Removal is necessary. This can be done by dishwasher, spray or immersion using cold or warm deionised water wash followed by rinsing with deionised water. Hot air dry.

Sn63Pb37 / Sn62Pb36Ag2 Reflow profile





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STORAGE AND PACKAGING

Packaging: jars of 250g, 400g - other on request.

Storage: in original container between 2 and 10°C for up to 6 months. Wait until the pot has reached the ambient temperature before opening to avoid water condensation on the surface of the paste. Once opened, do not return to the fridge, then can be kept at ambient conditions for one week.

Additional information:

Our manufacturing processes have been subjected to FMECA analysis (equivalent of AMDEC in France).

We cannot anticipate any and all conditions and situations under which the information and our products or the combination of both with others will be used. We do not assume any liability in the safety and suitability of our products alone or in combination with others. Users must make their own tests to determine the safety and suitability of each product used alone or with other products for their own use. Except any previous written agreement, our products are sold without guarantee and customers must assume all liability for any loss or damage suffered by themselves or by third parties, either from handling or use of our products alone or with others. In case of any difference or variation seen during the use of the products we request that you contact our technical department.